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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Teck Kheng Lee

Serial No.: 10/800,058

Filed: March 12, 2004

For: INNOVATIVE SOLDER BALL PAD
STRUCTURE TO EASE DESIGN RULE,
METHODS OF FABRICATING SAME
AND SUBSTRATES, ELECTRONIC
DEVICE ASSEMBLIES AND SYSTEMS
EMPLOYING SAME

Confirmation No.: 8448

Examiner: Unknown

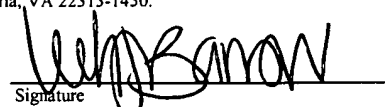
Group Art Unit: 2814

Attorney Docket No.: 2269-5351.1US

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

June 9, 2004
Date


Signature

Leah J. Barrow
Name (Type/Print)

PRELIMINARY AMENDMENT

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Prior to examination of the above-referenced patent application on the merits, entry of the amendments as set forth herein is respectfully solicited.

Amendments to the Specification begin on page 3 of this paper.

Amendments to the Abstract appear on page 14 of this paper.

Amendments to the Claims are reflected in the listing which begins on page 15 of this paper.

Amendments to the Drawings appear on page 19 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 20 of this paper.

An **Appendix** including amended drawing figures is attached following page 20 of this paper.